

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional)

BUR920040182US1

Application Number

10/711,418

Applicant(s)

Fen Chen et al.

Filing Date

09/17/2004

Group Art Unit

2825

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

U.S. PATENT APPLICATION PUBLICATIONS

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FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
SW		EP 1 376 680 A1	02.01.2004	European Patent Office				✓

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

SW		USING THE TEMPERATURE COEFFICIENT OF THE RESISTANCE (TCR) AS EARLY RELIABILITY INDICATOR FOR STRESSVOIDING RISKS IN CU INTERCONNECTS, by A. von Glasow et al., Copyright 2003, pp. 126-131.						

EXAMINER

/Stacy Whitmore/

DATE CONSIDERED

10/16/2006

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

IDS - 09/17/2004

ELECTRONIC INFORMATION DISCLOSURE STATEMENT
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Electronic Version v18

Stylesheet Version v18.0

Title of Invention	NON-DESTRUCTIVE EVALUATION OF MICROSTRUCTURE AND INTERFACE ROUGHNESS OF ELECTRICALLY CONDUCTING LINES IN SEMICONDUCTOR INTEGRATED CIRCUITS IN DEEP SUB-MICRON REGIME																																				
 Application Number : Confirmation Number: First Named Applicant: Fen Chen Attorney Docket Number: BUR920040182US1 Art Unit: 2825 Examiner: S. Whitmore Search string: (6603321 or 20010046276).pn US Patent Documents Note: Applicant is not required to submit a paper copy of cited US Patent Documents <table border="1"><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr><tr><td>SW</td><td>1</td><td>6603321</td><td>2003-08-05</td><td>Filippi, Jr. et al</td><td></td><td></td><td></td></tr></table> US Published Applications Note: Applicant is not required to submit a paper copy of cited US Published Applications <table border="1"><tr><th>init</th><th>Cite.No.</th><th>Pub. No.</th><th>Date</th><th>Applicant</th><th>Kind</th><th>Class</th><th>Subclass</th></tr><tr><td>SW</td><td>1</td><td>20010046276</td><td>2001-11-29</td><td>Schneider et al</td><td></td><td></td><td></td></tr></table> Signature <table border="1"><tr><td>Examiner Name</td><td>Date</td></tr><tr><td>/Stacy Whitmore/</td><td>10/16/2006</td></tr></table>		init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	SW	1	6603321	2003-08-05	Filippi, Jr. et al				init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass	SW	1	20010046276	2001-11-29	Schneider et al				Examiner Name	Date	/Stacy Whitmore/	10/16/2006
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